



3.3V CMOS 18-BIT UNIVERSAL BUS TRANSCEIVER WITH 3 STATE OUTPUTS, 5 VOLT TOLERANT I/O

IDT74LVC16601A

FEATURES:

- Typical $t_{SK(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
> 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP
and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to +85°C
- $V_{CC} = 3.3V \pm 0.3V$, Normal Range
- $V_{CC} = 2.7V$ to 3.6V, Extended Range
- CMOS power levels (0.4μW typ. static)
- All inputs, outputs and I/O are 5 Volt tolerant
- Supports hot insertion

Drive Features for LVC16601A:

- High Output Drivers: $\pm 24mA$
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

The LVC16601A 18-bit universal bus transceiver is built using advanced dual metal CMOS technology. This 18-bit universal bus transceiver combines D-type latches and D-type flip-flops to allow data flow in transparent, latched and clocked modes.

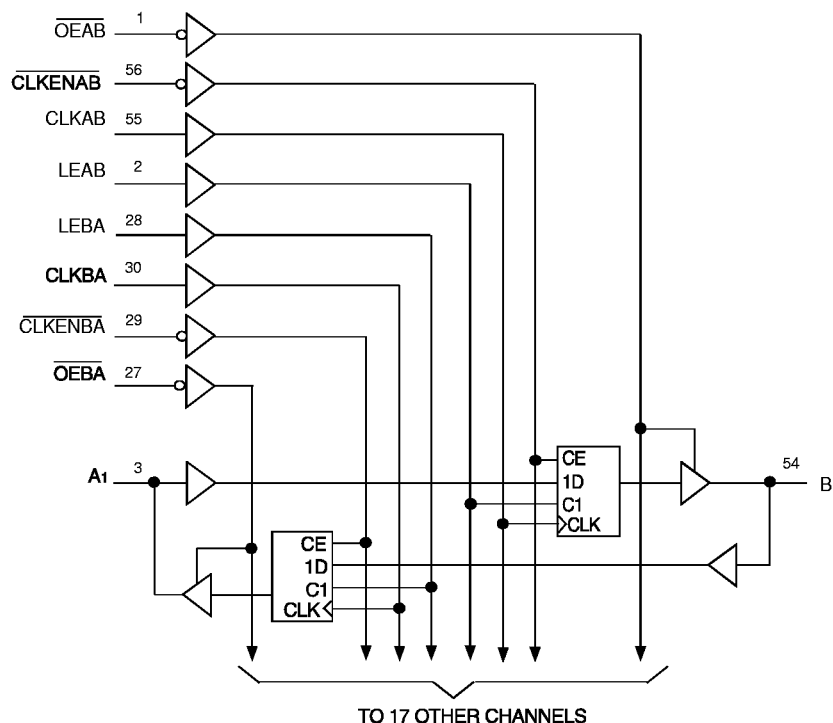
Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs.

For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the LOW-to-HIGH transition of CLKAB. Output enable $\overline{OEAB}$ is active low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B but uses $\overline{OEBA}$, LEBA, CLKBA and $\overline{CLKENBA}$.

All pins can be driven from either 3.3V or 5V devices. This feature allows the use of this device as a translator in a mixed 3.3V/5V supply system.

The LVC16601A has been designed with a $\pm 24mA$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

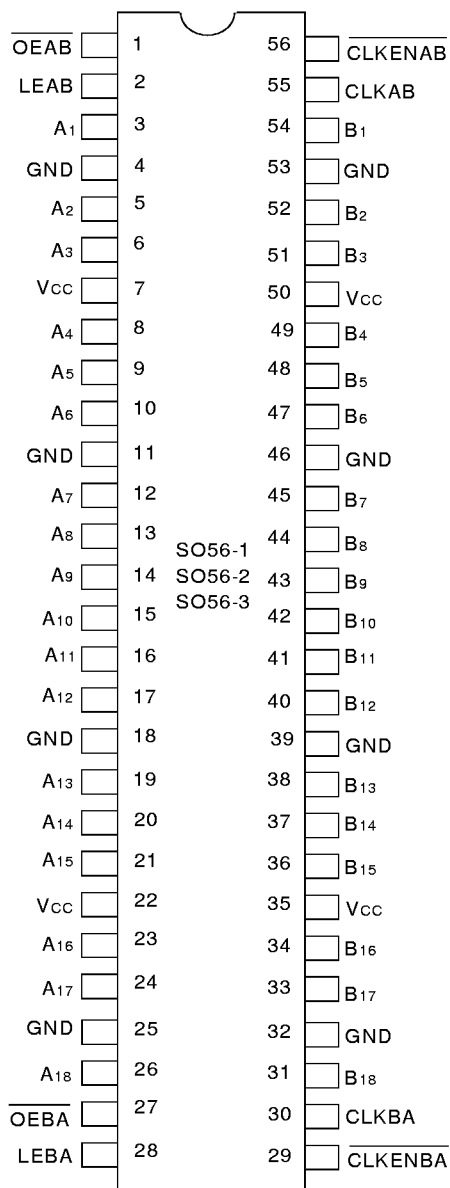
Functional Block Diagram



EXTENDED COMMERCIAL TEMPERATURE RANGE

MARCH 1999

PIN CONFIGURATION



SSOP/TSSOP/TVSOP
TOP VIEW

PIN DESCRIPTION

Pin Names	Description
$\overline{OEAB}$	A-to-B Output Enable Input (Active LOW)
$\overline{OEBA}$	B-to-A Output Enable Input (Active LOW)
LEAB	A-to-B Latch Enable Input
LEBA	B-to-A Latch Enable Input
CLKAB	A-to-B Clock Input
CLKBA	B-to-A Clock Input
Ax	A-to-B Data Inputs or B-to-A 3-State Outputs
Bx	B-to-A Data Inputs or A-to-B 3-State Outputs
$\overline{CLKENAB}$	A-to-B Clock Enable Input (Active LOW)
$\overline{CLKENBA}$	B-to-A Clock Enable Input (Active LOW)

ABSOLUTE MAXIMUM RATINGS (1)

Symbol	Description	Max.	Unit
$V_{TERM}^{(2)}$	Terminal Voltage with Respect to GND	-0.5 to +6.5	V
$V_{TERM}^{(3)}$	Terminal Voltage with Respect to GND	-0.5 to +6.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-50 to +50	mA
IIK IOL	Continuous Clamp Current, $V_I < 0$ or $V_O < 0$	-50	mA
ICC ISS	Continuous Current through each VCC or GND	±100	mA

LVC Link

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VCC terminals.
- All terminals except VCC.

CAPACITANCE ($T_A = +25^\circ\text{C}$, $f = 1.0\text{MHz}$)

Symbol	Parameter(1)	Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	$V_{IN} = 0\text{V}$	4.5	6	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0\text{V}$	6.5	8	pF
$C_{I/O}$	I/O Port Capacitance	$V_{IN} = 0\text{V}$	6.5	8	pF

LVC Link

NOTE:

- As applicable to the device type.

FUNCTION TABLE (1, 2)

Inputs					Outputs
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	Ax	Bx
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	$B_0^{(3)}$
L	L	L	↑	L	L
L	L	L	↑	H	H
L	L	L	L	X	$B_0^{(3)}$
L	L	L	H	X	$B_0^{(4)}$

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
↑ = LOW-to-HIGH Transition
- A-to-B data flow is shown. B-to-A data flow is similar but uses $\overline{OEBA}$, LEBA, CLKBA and $\overline{CLKENBA}$.
- Output level before the indicated steady-state input conditions were established.
- Output level before the indicated steady-state input conditions were established, provided that CLKAB was HIGH before LEAB went LOW.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V_{IH}	Input HIGH Voltage Level	$V_{CC} = 2.3\text{V}$ to 2.7V		1.7	—	—	V
		$V_{CC} = 2.7\text{V}$ to 3.6V		2	—	—	
V_{IL}	Input LOW Voltage Level	$V_{CC} = 2.3\text{V}$ to 2.7V		—	—	0.7	V
		$V_{CC} = 2.7\text{V}$ to 3.6V		—	—	0.8	
I_{IH} I_{IL}	Input Leakage Current	$V_{CC} = 3.6\text{V}$	$V_I = 0$ to 5.5V	—	—	± 5	μA
I_{OZH} I_{OZL}	High Impedance Output Current (3-State Output pins)	$V_{CC} = 3.6\text{V}$	$V_O = 0$ to 5.5V	—	—	± 10	μA
I_{OFF}	Input/Output Power Off Leakage	$V_{CC} = 0\text{V}$, V_{IN} or $V_O \leq 5.5\text{V}$		—	—	± 50	μA
V_{IK}	Clamp Diode Voltage	$V_{CC} = 2.3\text{V}$, $I_{IN} = -18\text{mA}$		—	-0.7	-1.2	V
V_H	Input Hysteresis	$V_{CC} = 3.3\text{V}$		—	100	—	mV
I_{CC1} I_{CC2} I_{CC3}	Quiescent Power Supply Current	$V_{CC} = 3.6\text{V}$	$V_{IN} = \text{GND}$ or V_{CC}	—	—	10	μA
			$3.6 \leq V_{IN} \leq 5.5\text{V}^{(2)}$	—	—	10	
ΔI_{CC}	Quiescent Power Supply Current Variation	One input at $V_{CC} - 0.6\text{V}$ other inputs at V_{CC} or GND		—	—	500	μA

LVC Link

NOTES:

1. Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.
2. This applies in the disabled state only.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = 2.3\text{V}$ to 3.6V	$I_{OH} = -0.1\text{mA}$	$V_{CC} - 0.2$	—	V
		$V_{CC} = 2.3\text{V}$	$I_{OH} = -6\text{mA}$	2	—	
		$V_{CC} = 2.3\text{V}$	$I_{OH} = -12\text{mA}$	1.7	—	
		$V_{CC} = 2.7\text{V}$		2.2	—	
		$V_{CC} = 3.0\text{V}$		2.4	—	
		$V_{CC} = 3.0\text{V}$	$I_{OH} = -24\text{mA}$	2.2	—	
V_{OL}	Output LOW Voltage	$V_{CC} = 2.3\text{V}$ to 3.6V	$I_{OL} = 0.1\text{mA}$	—	0.2	V
		$V_{CC} = 2.3\text{V}$	$I_{OL} = 6\text{mA}$	—	0.4	
			$I_{OL} = 12\text{mA}$	—	0.7	
		$V_{CC} = 2.7\text{V}$	$I_{OL} = 12\text{mA}$	—	0.4	
		$V_{CC} = 3.0\text{V}$	$I_{OL} = 24\text{mA}$	—	0.55	

LVC Link

NOTE:

1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$.

OPERATING CHARACTERISTICS, $V_{CC} = 3.3V \pm 0.3V$, $T_A = 25^\circ C$

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per transceiver Outputs enabled	$C_L = 0pF$, $f = 10MHz$		pF
CPD	Power Dissipation Capacitance per transceiver Outputs disabled			pF

SWITCHING CHARACTERISTICS (1)

Symbol	Parameter		$V_{CC} = 2.7V$		$V_{CC} = 3.3V \pm 0.3V$		Unit
			Min.	Max.	Min.	Max.	
tPLH tPHL	Propagation Delay Ax to Bx or Bx to Ax		—	5.4	—	4.6	ns
tPLH tPHL	Propagation Delay LEBA to Ax, LEAB to Bx		—	6.2	—	5.2	ns
tPLH tPHL	Propagation Delay CLKBA to Ax, CLKAB to Bx		—	6.3	—	5.3	ns
tPZH tPZL	Output Enable Time $\overline{OEBA}$ to Ax, $\overline{OEAB}$ to Bx		—	6.8	—	5.6	ns
tPHZ tPLZ	Output Disable Time $\overline{OEBA}$ to Ax, $\overline{OEAB}$ to Bx		—	6	—	5.2	ns
tSU	Set-up Time, HIGH or LOW Ax to CLKAB, Bx to CLKBA		1.5	—	1.5	—	ns
tH	Hold Time HIGH or LOW Ax after CLKAB, Bx after CLKBA		0.8	—	0.8	—	ns
tSU	Set-up Time HIGH or LOW Ax to LEAB, Bx to LEBA	Clock LOW	1	—	1	—	ns
		Clock HIGH	1	—	1	—	ns
tSU	Set-up Time, $\overline{CLKENAB}$ to CLKAB		2.1	—	2.1	—	ns
tSU	Set-up Time, $\overline{CLKENBA}$ to CLKBA		2.1	—	2.1	—	ns
tH	Hold Time, HIGH or LOW Ax after LEAB, Bx after LEBA		1.8	—	1.8	—	ns
tH	Hold Time, $\overline{CLKENAB}$ after CLKAB		0.5	—	0.5	—	ns
tH	Hold Time, $\overline{CLKENBA}$ after CLKBA		0.5	—	0.5	—	ns
tw	LEAB or LEBA Pulse Width HIGH		3	—	3	—	ns
tw	CLKAB or CLKBA Pulse Width HIGH or LOW		3	—	3	—	ns
tSK(o)	Output Skew ⁽²⁾		—	—	—	500	ps

NOTES:

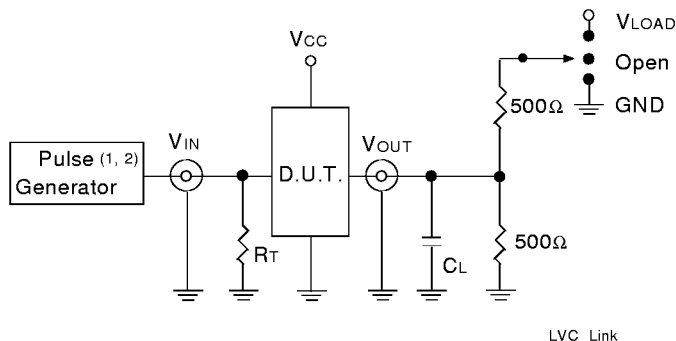
1. See test circuits and waveforms. $T_A = -40^\circ C$ to $+85^\circ C$.
2. Skew between any two outputs of the same package and switching in the same direction.

TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} (1) = 3.3V ± 0.3V	V _{CC} (1) = 2.7V	V _{CC} (2) = 2.5V ± 0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

TEST CIRCUITS FOR ALL OUTPUTS



DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

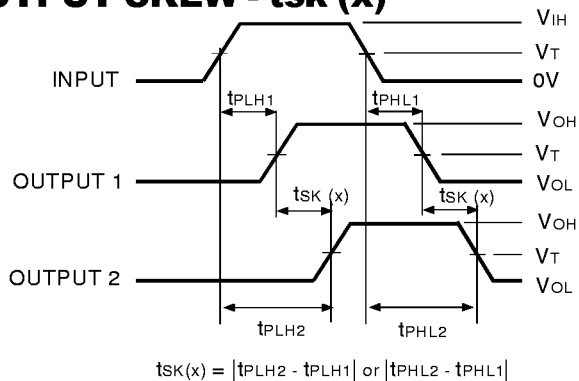
NOTE:

1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

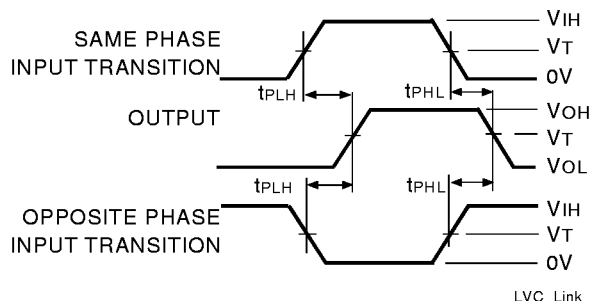
OUTPUT SKEW - t_{SK} (x)



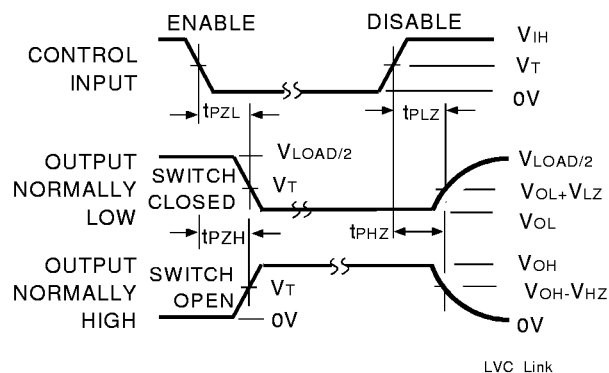
NOTES:

1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



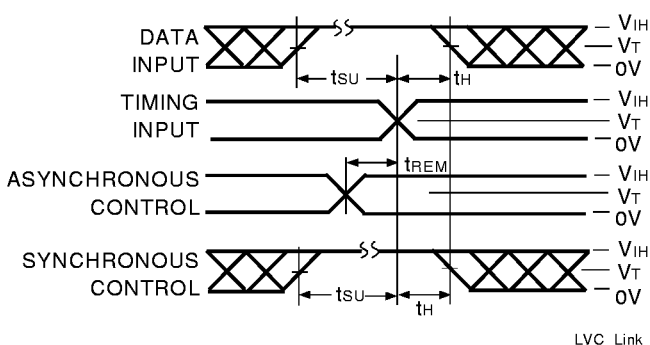
ENABLE AND DISABLE TIMES



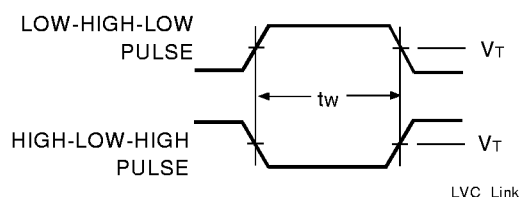
NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



PULSE WIDTH



ORDERING INFORMATION

IDT	XX	LVC	X	XX	XXXX	XX	
	Temp. Range		Bus-Hold	Family	Device Type	Package	
						PV	Shrink Small Outline Package (SO56-1)
						PA	Thin Shrink Small Outline Package (SO56-2)
						PF	Thin Very Small Outline Package (SO56-3)
					601A		18-Bit Universal Bus Transceiver
					16		Double-Density with Resistors, $\pm 24\text{mA}$
					Blank		No Bus-hold
					74		-40°C to +85°C



CORPORATE HEADQUARTERS

2975 Stender Way
 Santa Clara, CA 95054

for SALES:

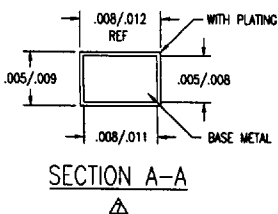
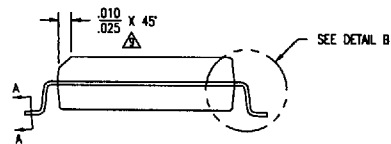
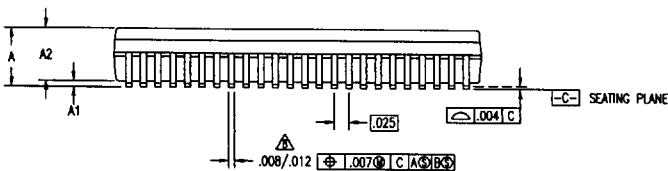
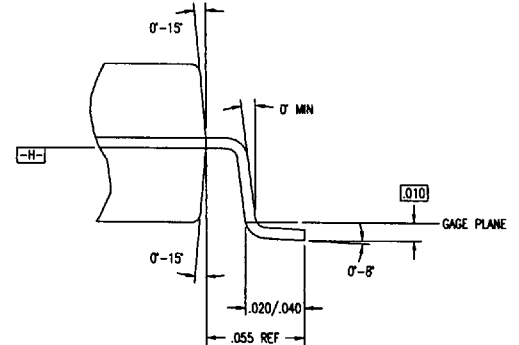
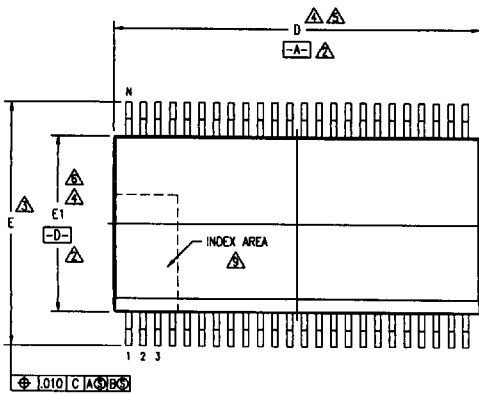
800-345-7015 or 408-727-6116
 fax: 408-492-8674
www.idt.com*

*To search for sales office near you, please click the sales button found on our home page or dial the 800# above and press 2.
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PACKAGE DIAGRAM OUTLINES

SSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	



TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2075 Slender Way, Santa Clara, CA 95054	
XXX	±	PHONE: (408) 727-8118	
XXX		FAX: (408) 482-8874	
XXX		TWC: 910-338-2070	
APPROVALS	DATE	TITLE	REV
DRAWN	08/15/90	PV PACKAGE OUTLINE	02
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
		SIZE C	
		DRAWING No. PSC-4029	
		DO NOT SCALE DRAWING	

PACKAGE DIAGRAM OUTLINES SSOP (Continued)

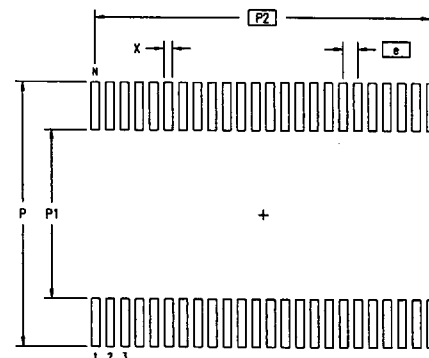
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WJ
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

DWG #		S048-1				DWG #		S056-1			
SYMBOL	JEDEC VARIATION				NOTE	JEDEC VARIATION				NOTE	
	AA			AB							
	MIN	NOM	MAX	MIN		NOM	MAX				
A	.095	.102	.110		.095	.102	.110				
A1	.008	.012	.016		.008	.012	.016				
A2	.088	.090	.092		.088	.090	.092				
D	.620	.625	.630	4,5	.720	.725	.730	4,5			
E	.395	.405	.420	3	.395	.405	.420	3			
E1	.291	.295	.299	4,6	.291	.295	.299	4,6			
N	48				56						

NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- ⚠ DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
- ⚠ DIMENSION E TO BE DETERMINED AT SEATING PLANE **-C-**
- ⚠ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE **-H-**
- ⚠ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE
- ⚠ DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE
- ⚠ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP
- ⚠ LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- ⚠ THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED
- 10 ALL DIMENSIONS ARE IN INCHES
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARIATION AA & AB

LAND PATTERN DIMENSIONS



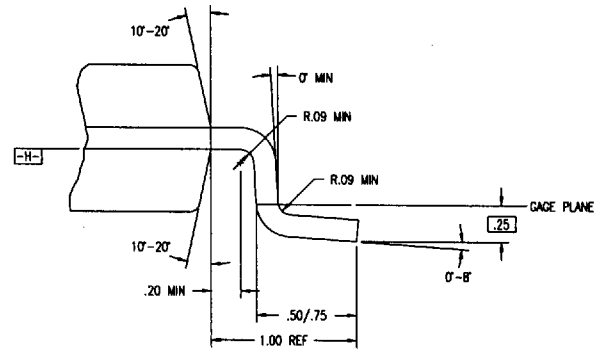
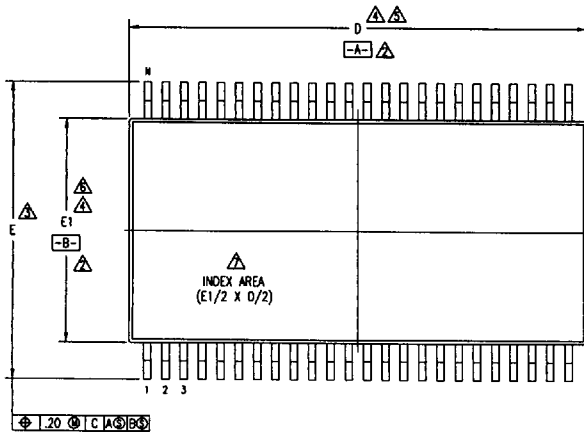
	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2075 Stoner Way, Santa Clara, CA 95054	
X.XX	±	PHONE: (408) 727-8116	
X.XXX	±	FAX: (408) 482-8874	
X.XXX	±	TW: 810-338-2070	
APPROVALS	DATE	TITLE	REV
DRN	06/15/90	PV PACKAGE OUTLINE	
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
		SIZE	REV
		C	02
		DRAWING No.	
		PSC-4029	
		DO NOT SCALE DRAWING	

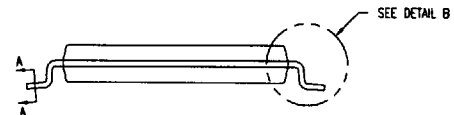
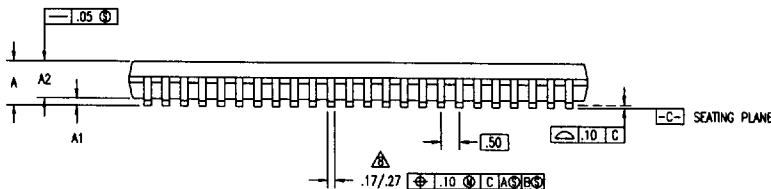
PACKAGE DIAGRAM OUTLINES

TSSOP

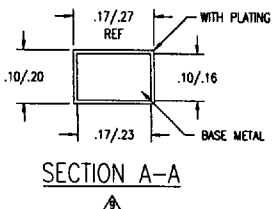
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	



DETAIL B



SEE DETAIL B



SECTION A-A

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Slender Way, Santa Clara, CA 95054	
XXX.X	±	PHONE: (408) 727-8118	
XXXX.X		FAX: (408) 492-8674	
XXXXX		TW: 910-336-2070	
APPROVALS	DATE	TITLE	REV
DRAWN	01/15/93	PA PACKAGE OUTLINE	
CHECKED		6.10 mm BODY WIDTH TSSOP	
		.50 mm PITCH	
		SIZE	DRAWING No.
		C	PSC-4039
			03
			DO NOT SCALE DRAWING

PACKAGE DIAGRAM OUTLINES TSSOP (Continued)

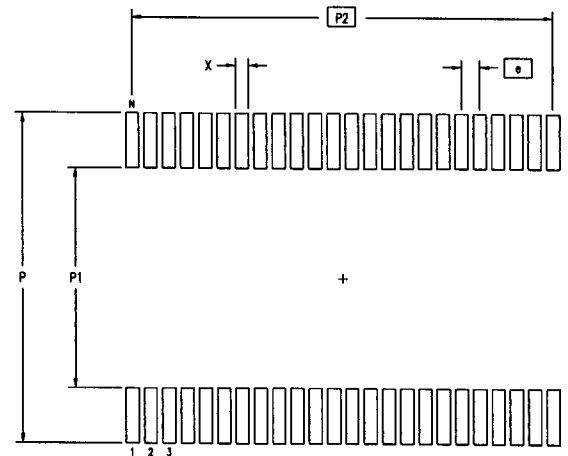
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SYMBOL	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE			
	ED				EE						
	MIN	NOM	MAX		MIN	NOM	MAX				
A	-	-	1.10		-	-	1.10				
A1	.05	-	.15		.05	-	.15				
A2	.85	1.00	1.05		.85	1.00	1.05				
D	12.40	12.50	12.60	4,5	13.90	14.00	14.10	4,5			
E	7.95	8.10	8.25	3	7.95	8.10	8.25	3			
E1	6.00	6.10	6.20	4,6	6.00	6.10	6.20	4,6			
N	48				56						

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS $\square$ -A- and $\square$ -B- TO BE DETERMINED AT DATUM PLANE $\square$ -H-
- DIMENSION E TO BE DETERMINED AT SEATING PLANE $\square$ -C-
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE $\square$ -H-
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- ALL DIMENSIONS ARE IN MILLIMETERS
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MQ-153, VARIATION ED & EE

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

LAND PATTERN DIMENSIONS



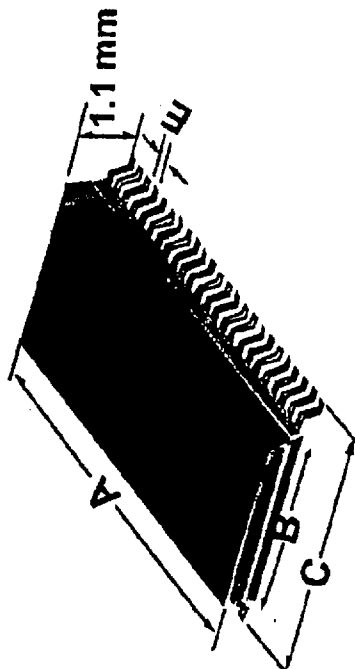
	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50 BSC		13.50 BSC	
X	.30	.40	.30	.40
e	.50 BSC		.50 BSC	
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Slender Way, Santa Clara, CA 95054	
XXX.X	±	PHONE: (408) 727-8118	
XXXX.XX		FAX: (408) 482-8874	
XXXX.XXX		TWC: 910-338-2070	
APPROVALS	DATE	TITLE	PA PACKAGE OUTLINE
DRAWN	01/19/93	6.10 mm BODY WIDTH TSSOP	
CHECKED		.50 mm PITCH	
		SIZE	C
		DRAWING No.	PSC-4039
		REV	03
		DO NOT SCALE DRAWING	



TVSOP

The Most Compact Double Density Package

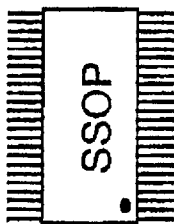


TVSOP Package	Typical Dimensions (in mm)				Area (mm ²)
	A	B	C	E	
48 Pin	9.80	4.40	6.40	0.40	63.00
56 Pin	11.30	4.40	6.40	0.40	72.30
80 Pin	17.00	6.10	8.10	0.40	137.80
100 Pin	20.80	6.10	8.10	0.40	168.50



Double Density Packaging

48-Pin



16.0 x 10.3 x 2.6 mm
pin pitch = 0.635 mm
Area = 164.8 mm²

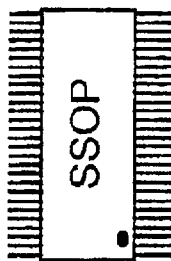


12.5 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 101.3 mm²



9.8 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 62.7 mm²

56-Pin



18.4 x 10.3 x 2.6 mm
pin-pitch = 0.635 mm
Area = 189.5 mm²



14.0 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 113.4 mm²



11.3 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 72.3 mm²

TVSOP	Area (mm ²)	%Smaller Than SSOP	%Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0